

ABSTRACT OF THE DISCLOSURE

Disclosed is a camera module in which an operational defect (generation of a ghost image) as a result of a reduction in thickness is eliminated. A camera module 2 includes a substrate 10 provided with a through-hole 14 for light transmission, a light receiving portion 15 provided on one side, an imaging element 11 flip chip mounted on one side of the substrate such that the light receiving portion 15 is exposed through the through-hole 14, and a shielding layer 22 on the back surface of the element on the opposite side of the light receiving portion 15, and a lens unit 12 mounted on the other side of the substrate 10.